

## REMARKS

The present filing is responsive to the Office Action.

### Summary of the Response

Claim 1 has been amended. Claims 11-19 have been previously withdrawn. New claim 20 has been added. Claims 1-20 remain pending in this application. Reexamination and reconsideration of the present application as amended are respectfully requested.

### Claim Objections

Claim 1 has been amended to recited “attaching the image sensor chip to the substrate”, as the Examiner suggested by examining the claim with this interpretation.

### Claim Rejections Under 35 USC 102

Claims 1-5 and 8-10 are rejected under 35 U.S.C. 102(e) as being anticipated by Lam (US 6,541,284). Claims 6-7 are rejected under 35 U.S.C. 103(a) as being unpatentable over Lam (US 6,541,284). These rejections are respectfully traversed.

The claimed invention is directed to a method for assembling a camera module, by first positioning a lens in the direction of its optical axis and with respect to a substrate, before attaching an image sensor chip to the substrate. Originally presented claim 1 recites “aligning a detector of a measuring device with the optical axis of the lens; ... removing the measuring device ....”. Lam does not disclose a separate measuring device that has a detector, which is in addition to an image sensor chip, and which is being removed during the process. Lam instead

discloses aligning its lens 89 and frame structure 91 with respect to an image sensor 101 (see, Fig. 14 in Lam). The image sensor 101 is not being removed after alignment of the lens 89 and frame structure 91. There is clearly no separate measuring device having a detector, and further which is being removed during the process. The image sensor 101 is not removed at any time after assembly, let alone being removed after alignment of the lens 89 and frame structure 91. There is no reason to remove the image sensor 101, since the same image sensor 101 is used for alignment of the lens 89. Lam therefore does not disclose the recited combination of steps including aligning a detector of a measuring device with the optical axis of the lens, and removing the measuring device.

The Examiner referred to item 97 to correspond to the recited image sensor chip, and item 115 to correspond to the recited measuring device. However, item 97 is a chip package including a lens assembly and an image sensor, and item 115 is an “electronic focus testing equipment”. The Examiner has not identified any detector of such electronic focus testing equipment, and further which detector is aligned with the optical axis of the lens, as required by claim 1, let alone how such measuring device is removed (i.e., from the optical axis of the lens). The Examiner must identify the corresponding structure in Lam to reject the claims, or withdraw the rejection.

Accordingly, independent claim 1 is not anticipated by Lam. All claims dependent therefrom (including the withdrawn claims 11-19) are likewise not anticipated by Lam for at least the above reasons. The obviousness rejection of dependent claims 6 and 7 are also rendered moot in view of the traversal of the rejection of the base claim 1.

New dependent claim 20 has been added to round out the coverage of the present invention. Claim 20 further recites the measuring device is removed before the image sensor

chip is attached to the substrate, so as to align the light-sensitive surface of the image sensor chip with the optical axis of the lens. This further distinguishes from the assembly process disclosed in Lam.

## **CONCLUSION**

In view of all the foregoing, Applicant submits that the claims pending in this application are patentable over the references of record and are in condition for allowance. Such action at an early date is earnestly solicited. **The Examiner is invited to call the undersigned representative to discuss any outstanding issues that may not have been adequately addressed in this response.**

The Assistant Commissioner is hereby authorized to charge any additional fees under 37 C.F.R. §§ 1.16 and 1.17 that may be required by this transmittal and associated documents, or to credit any overpayment to **Deposit Account No. 501288** referencing the attorney docket number of this application.

Respectfully submitted,

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